

40V, 3.5A Monolithic Step-Down Switching Regulator

1 Features

- 3.5A continuous output current capability
- Up to 98% duty
- 4.6V to 33V wide operating input range
- Integrated 40V, 80mΩ high side and 40V, 50mΩ low side power MOSFET switches
- Up to 97% efficiency
- External Soft-Start limits the inrush current at turn-on
- Fixed 160KHz Switching Frequency
- Pulse Skipping Mode to Achieve High Light Load Efficiency
- Frequency jittering to ease EMI Issue
- Peak Current-Mode Control
- Cycle-by-Cycle Over Current Protection
- Input over-voltage protection
- Output Over-Voltage Protection
- Output short protection
- Over-Temperature Protection
- Available in ESOP8 Package

2 Applications

- 9-V, 12-V and 24-V Distributed Power Systems
- Consumer Applications Such as Home Appliances, Set-Top Boxes, CPE Equipment, LCD Displays, Peripherals, and Battery Chargers
- Industrial and Car Entertainment Power Supplies

3 Description

The PL82055 is a monolithic synchronous buck regulator with wide operating input voltage range from 4.6 to 33V. Current mode control with internal slope compensation is implemented to reduce component count. PL82055 also features a light load pulse skipping mode, which allows for a power loss reduction from the input power supply to the system at light loading. Frequency spread spectrum operation is introduced for EMI reduction. A cycle-by-cycle current limit with frequency fold back protects the IC at over loading condition.

4 Typical Application Schematic

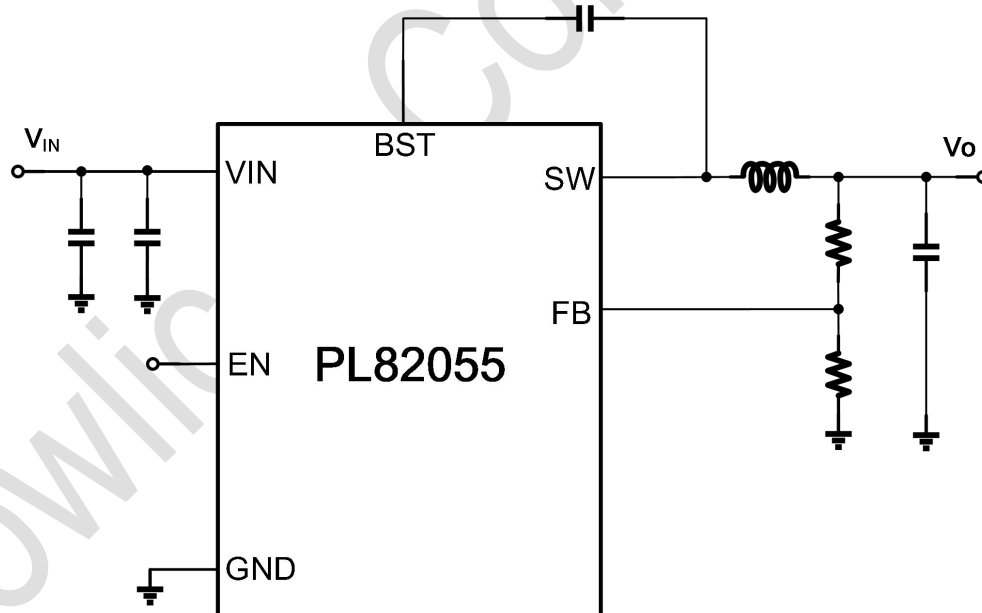
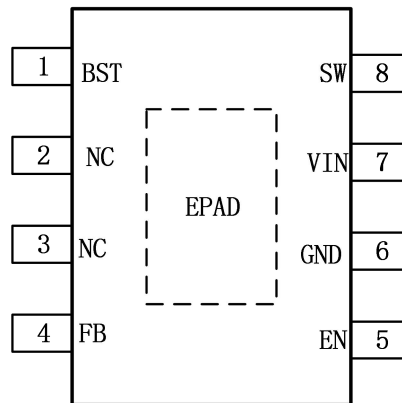


Fig. 1 Application Schematic

5 Pin Configuration and Functions

Fig. 2 Pin-Function

Pin		Description
Number	Name	
1	BST	Boot-Strap pin Connect a 0.1 μ F or greater capacitor between SW and BST to power the high side gate driver.
2	NC	No connect
3	NC	No connect
4	FB	Output voltage feedback pin
5	EN	Enable Input. EN is a digital input that turns the regulator on or off. Drive EN high to turn on the regulator; low to turn it off. EN pin is pulled to VIN internally by a larger resistor.
6	GND	Ground
7	VIN	Power Input. VIN supplies the power to the IC. Supply VIN with a 4.6V to 33V power source. Bypass VIN to GND with a large capacitor and at least another 0.1 μ F ceramic capacitor to eliminate noise on the input to the IC. Put the capacitors close to VIN and GND pins.
8	SW	Power Switching pin. Connect this pin to the switching node of inductor.
EPAD	GND	Ground

6 Device Marking Information

Order Information	Label Part NO.	Package	Package Qty	Top Marking
PL82055	PL82055IES08A	ESOP-8	4000	82055 RAAYMD

PL82055: Part Number

RAAYMD RAA: Lot Number. YMD: Package Date Code

7 Specifications

7.1 Absolute Maximum Ratings^(Note1)

Symbol	Description	Rating	Unit
VIN	VIN to GND Voltage	-0.3 to +40	V
BST	BST to SW Voltage	-0.3 to +6.5	V
SW	SW to GND Voltage	-0.3 to +40	V
Others	EN, FB Voltage	-0.3 to +6.5	V

7.2 Handling Ratings

PARAMETER	DEFINITION	MIN	MAX	UNIT
T _{ST}	Storage Temperature Range	-65	+150	°C
T _J	Junction Temperature		+150	°C
T _L	Lead Temperature		+260	°C
V _{ESD}	HBM Human body model		2	kV

7.3 Recommended Operating Conditions^(Note 2)

Symbol	Description	Rating	Unit
VIN	VIN Voltage	+5 to +33	V
SW	SW Voltage	0 to +33	V
BST	BST Voltage	0 to SW+5	V
Others	EN, FB Voltage	0 to +5	V
T _A	Operating Ambient Temperature Range	-40 to +125	°C

7.4 Thermal Information^(Note 3)

Symbol	Description	ESOP8	Unit
θ_{JA}	Junction to ambient thermal resistance	56	°C/W
θ_{Jc}	Junction to case thermal resistance	45	

Notes:

- 1) Exceeding these ratings may damage the device.
- 2) The device function is not guaranteed outside of the recommended operating conditions.
- 3) Measured on approximately 1" square of 1 oz copper.

7.5 Electrical Characteristics

V_{IN} = 12 V, T_J = - 40 °C to 125 °C , Typical values are at T_J = 25 °C , unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Type	Max	Unit
SUPPLY VOLTAGE (VIN)						
V _{IN_max}	Buck input stand off voltage		40			V
V _{IN}	Buck input voltage range		4.6		33	V
V _{IN_UVLO}	VIN UVLO voltage	VIN rising		4.6		V
		VIN falling		4.1		V
V _{IN_OVP}	VIN over voltage	VIN rising		33		V
		VIN falling		30		V
I _Q	VIN Shutdown Current	V _{EN} = 0, V _{IN} = 12V		10		uA
CONTROL LOOP						
F _{buck}	Buck switching frequency range			160		kHz
f _{jitter}	Frequency spread spectrum in percentage of F _{buck}			±6		%
FB	FB Voltage			0.8		V
VO _{UT_OVP}	OUTPUT Over-voltage threshold			1.1*FB		V
D _{max}	Maximum Duty Cycle			98		%
T _{on}	Minimum On Time			100		ns
ILIMIT	Peak inductor current limit			6.5		A
MOSFET AND PROTECTION						
I _{chg_ss}	Soft-Start Charge Current			2		uA
R _{DS(ON)_H}	High-Side Switch On-Resistance			80		mΩ
R _{DS(ON)_L}	Low-Side Switch On-Resistance			50		mΩ
T _{h_{sd}}	Thermal Shutdown			160		°C
T _{h_{sd}hys}	Thermal Shutdown Hysteresis			60		°C

Note:

4) Guaranteed by design, not tested in production

8 Typical Characteristics

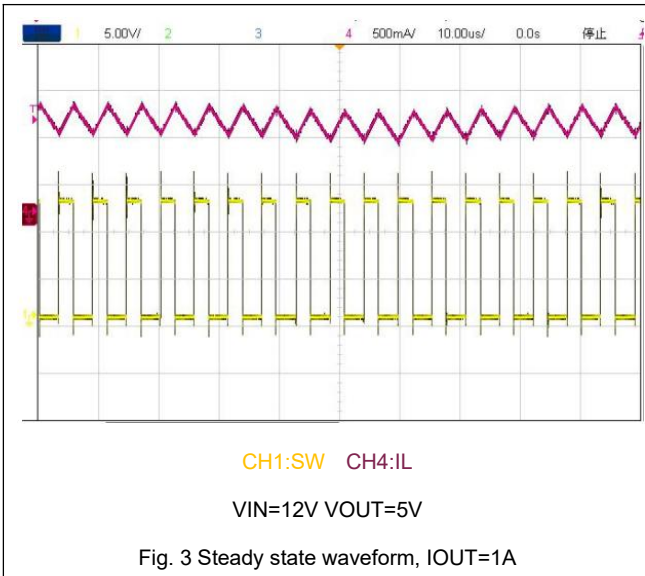


Fig. 3 Steady state waveform, IOUT=1A

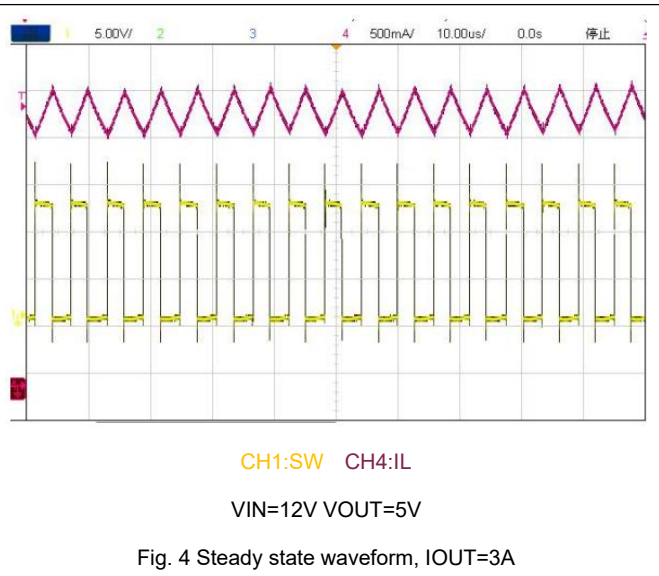


Fig. 4 Steady state waveform, IOUT=3A

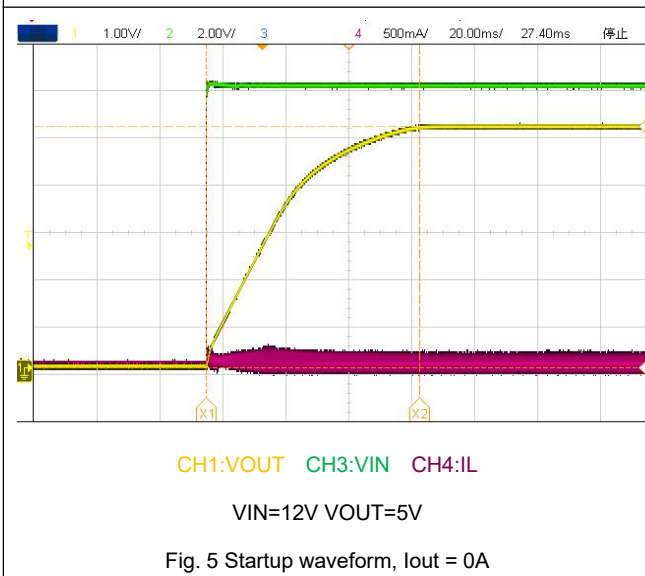


Fig. 5 Startup waveform, Iout = 0A

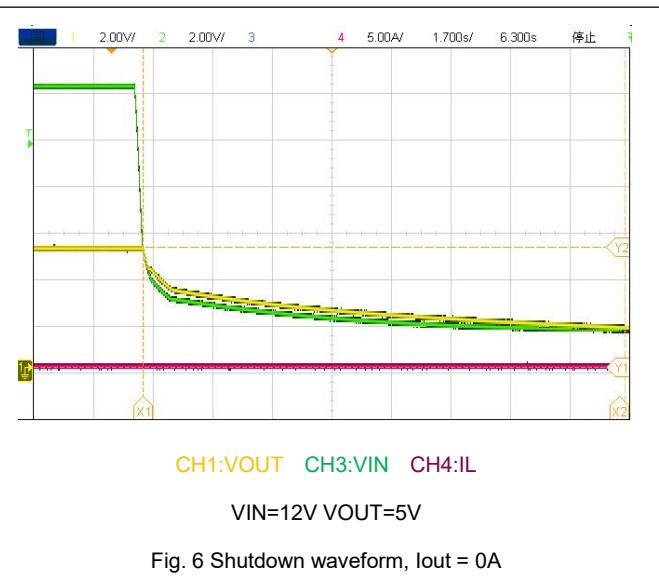


Fig. 6 Shutdown waveform, Iout = 0A

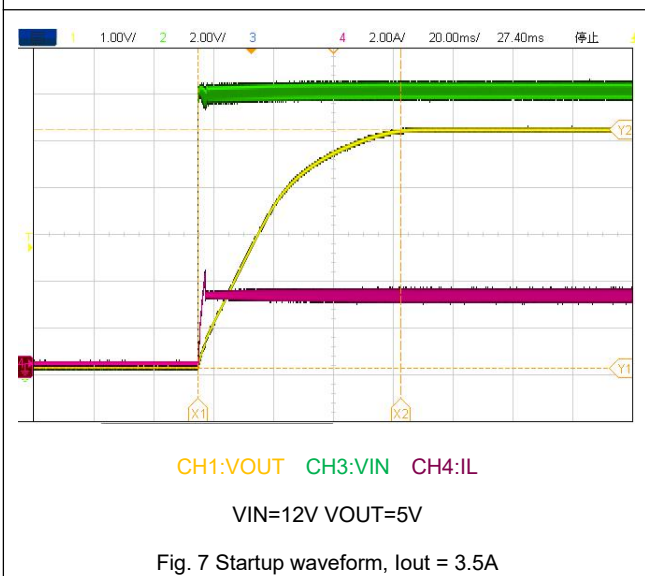


Fig. 7 Startup waveform, Iout = 3.5A

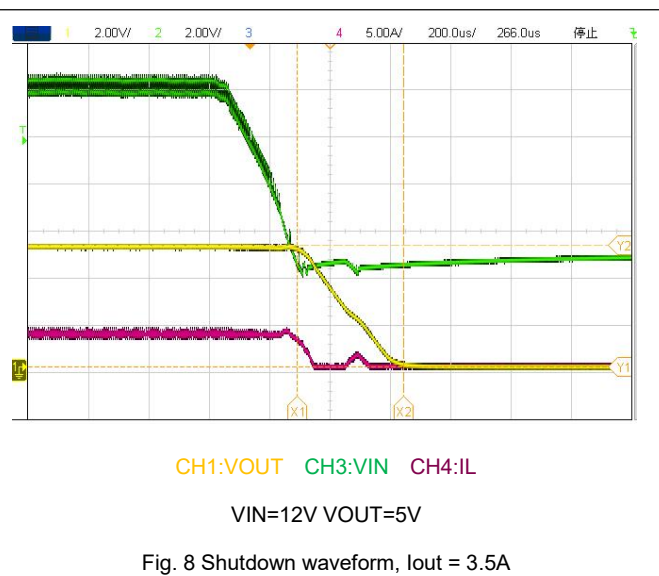
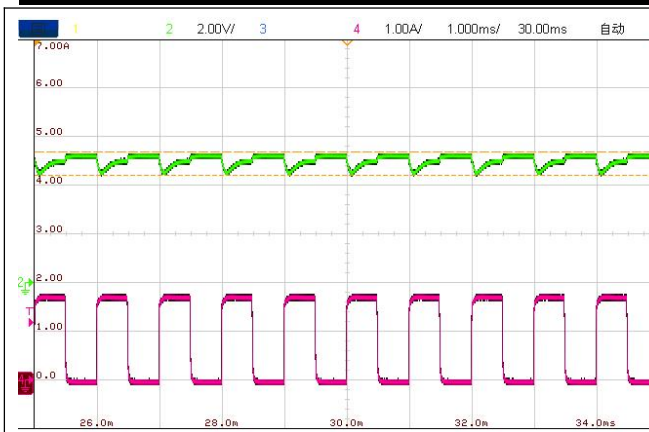


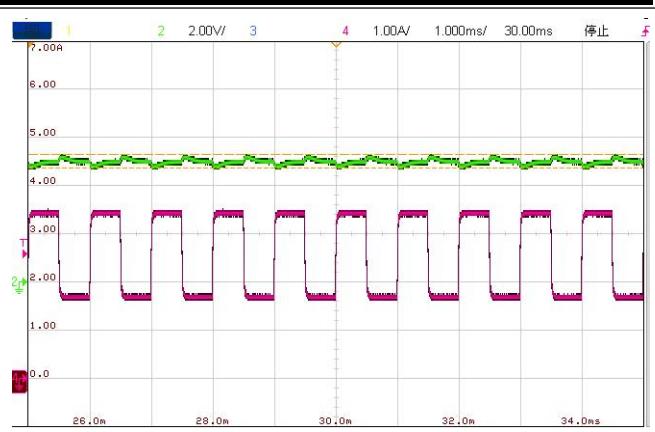
Fig. 8 Shutdown waveform, Iout = 3.5A



CH1:VOUT CH4:IOUT

VIN=12V ,VOUT=5V 0A-1.75A, 0.25A/us, 1KHZ, Duty50%

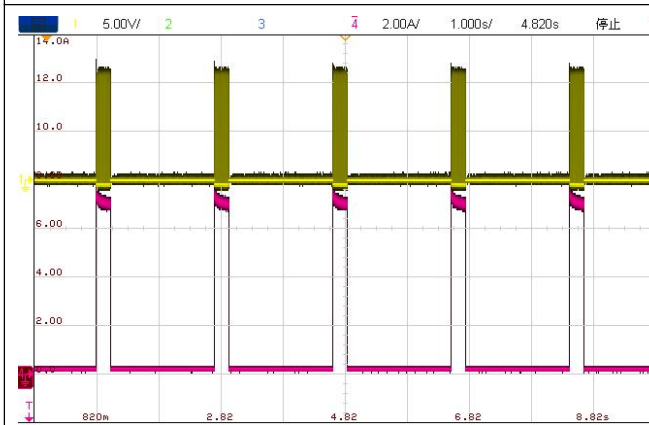
Fig. 9 Load Transient waveform



CH1:VOUT CH4:IOUT

VIN=12V ,VOUT=5V 1.75A-3.5A, 0.25A/us, 1KHZ, Duty50%

Fig. 10 Load Transient waveform



CH1:SW CH4:IL

VIN=12V VOUT=5V

Fig. 11 Short Circuit waveform

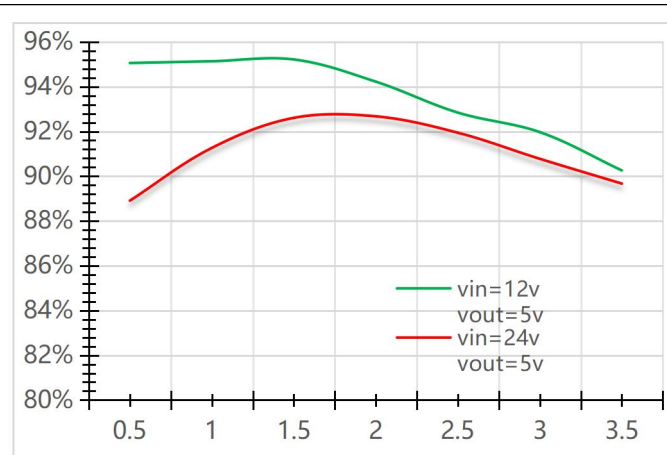


Fig. 12 efficiency curve

9. Detailed Description

9.1 Overview

The PL82055 is a 40V, 3.5A, step-down (buck) converter with an integrated N-channel MOSFET. To improve performance during line and load transients, the device implements a constant frequency, current mode control which reduces output capacitance and simplifies external frequency compensation design.

The PL82055 starts switching at VIN equal to 4.6 V. The bias voltage for the integrated high-side MOSFET is supplied by an external capacitor on the BST to SW pins. The boot capacitor voltage is monitored by an UVLO circuit and will turn the high-side MOSFET off when the voltage falls below a preset threshold of 2.1 V typically. To improve the efficiency at light load conditions, the PL82055 enters a special pulse skipping mode. The frequency foldback reduces the switching frequency during startup and over current conditions to help control the inductor current. The thermal shut down gives the additional protection under fault conditions.

9.2 Functional Block Diagram

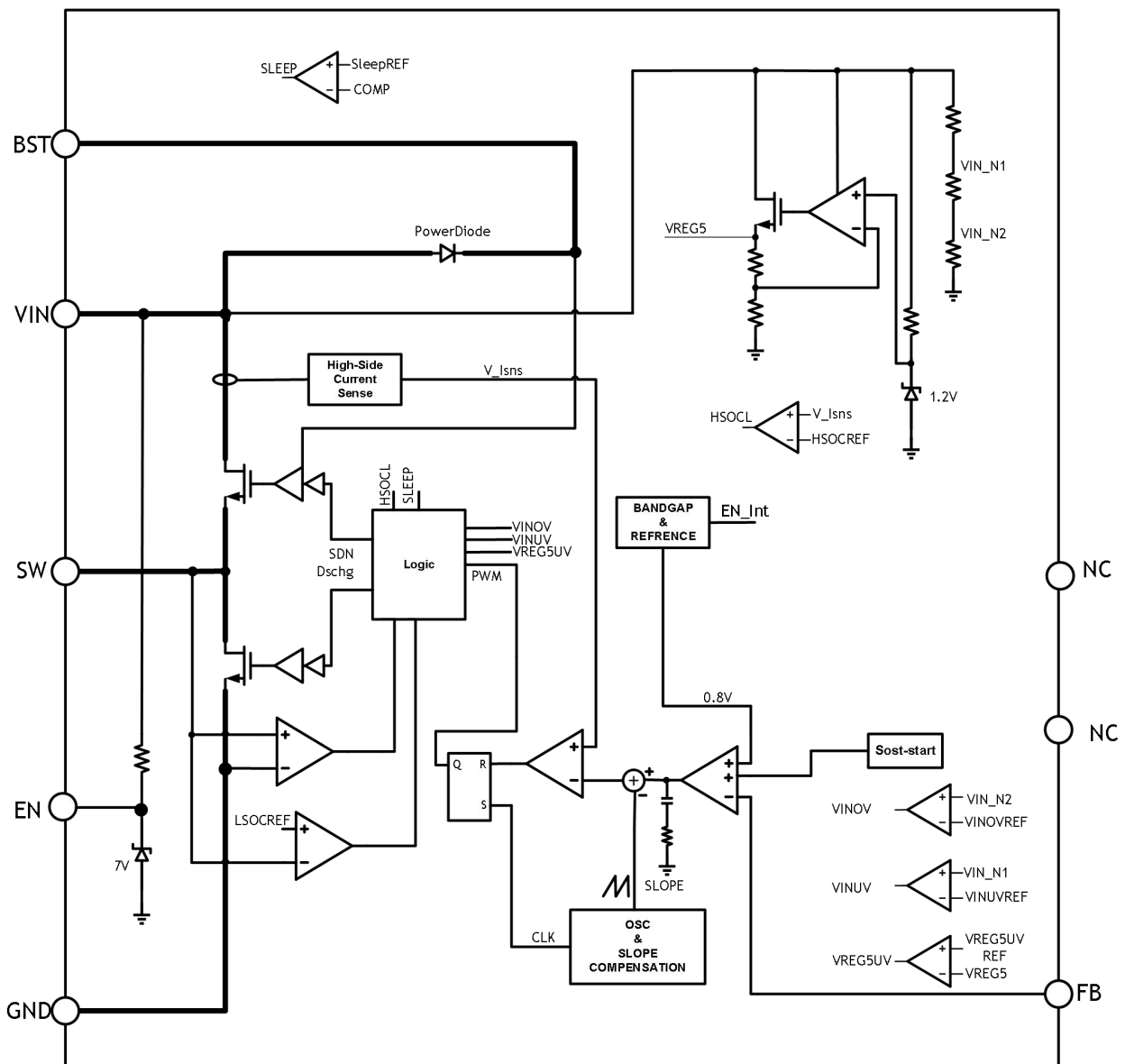


Fig. 9-2 PL82055 Diagram

9.3 Feature Description

9.3.1 Setting Output Voltage

The voltage reference system produces a $\pm 1.5\%$ initial accuracy voltage reference by scaling the output of a temperature stable bandgap circuit. The typical voltage reference is designed at 0.8 V.

$$V_{\text{out}} = V_{\text{FB}} \times \frac{R_1 + R_2}{R_2}$$

9.3.2 Bootstrap Voltage (BST)

The PL82055 has an integrated boot regulator and requires a 0.1- μF ceramic capacitor between the BST and SW pins to provide the gate drive voltage for the high-side MOSFET. A ceramic capacitor with an X7R or X5R grade dielectric is recommended because of the stable characteristics over temperature and voltage. To improve drop out, the PL82055 is designed to operate at 98% duty cycle as long as the BST to SW pin voltage is greater than 2.1 V typically.

9.3.3 Error Amplifier

The PL82055 has a transconductance amplifier for the error amplifier. The error amplifier compares the FB voltage to the internal effective voltage reference presented at the input of the error amplifier.

9.3.4 Spread Spectrum

In order to reduce EMI, PL82055 introduces frequency spread spectrum. The jittering span is $\pm 6\%$ of the switching frequency .

9.3.5 Peak Current Mode Control

PL82055 employs peak current mode control. The output voltage is sensed by an internal feedback resistor string on VOUT pin and fed to an internal error amplifier. The output of error amplifier will compare with high side current sense signal by an internal PWM comparator. When the second signal is higher than the first one, the PWM comparator will generate a turn-off signal to turn off high side switch. The output voltage of error amplifier will increase or decrease proportionally with the output load current. PL82055 has a cycle-by-cycle peak current limit feature inside to help maintain load current in a safe region.

9.3.6 Enable

PL82055 can be enabled by EN pin. EN pin internal threshold is set at 1.2V. EN pin has been pulled up inside. Customer can also adjust the startup voltage at input pin by this EN pin through resistor divider.

9.3.7 Thermal Shutdown

The internal thermal-shutdown circuitry forces the device to stop switching if the junction temperature exceeds 160°C typically. When the junction temperature drops below 100°C, IC will start to work again.

10 Application and Implementation

10.1 Inductor selection

An inductor is required to supply constant current to the load while being driven by the switched input voltage. A larger value inductor will result in less current ripple and lower output voltage ripple. However, the larger value inductor will have larger physical size, higher DC resistance, and/or lower saturation current. A good rule to calculate the inductance is to allow the peak-to-peak ripple current in the inductor to be approximately 25% of the maximum load current. At the same time, it is needed to make sure that the peak inductor current is below the inductor saturation current.

The inductance value can be calculated by:

$$L = \frac{V_{OUT}}{f_s \times \Delta I_L} \left(1 - \frac{V_{OUT}}{V_{IN}} \right)$$

Where V_{OUT} is the output voltage, V_{IN} is the input voltage, f_s is the switching frequency, and ΔI_L is the peak-to-peak inductor ripple current.

Choose an inductor that will not saturate under the maximum peak current. The peak inductor current can be calculated by:

$$I_{L,P} = I_{load} + \frac{V_{OUT}}{2 \times f_s \times L} \left(1 - \frac{V_{OUT}}{V_{IN}} \right)$$

Where I_{load} is the load current.

The choice of inductor material mainly depends on the price vs. size requirements and EMI constraints.

10.2 Input capacitors selection

The input current to the step-down converter is discontinuous, therefore a capacitor is required to supply the AC current to the converter. It is recommend to use low ESR capacitors to optimize the performance. Ceramic capacitor is preferred, but tantalum or low-ESR electrolytic capacitors may also meet the requirements. It is better to choose X5R or X7R dielectrics when using ceramic capacitors.

Since the input capacitor (C_{IN}) absorbs the input switching current, a good ripple current rating is required for the capacitor. The RMS current in the input capacitor can be estimated by:

$$I_{CIN} = I_{load} \times \sqrt{\frac{V_{OUT}}{V_{IN}} \times \left(1 - \frac{V_{OUT}}{V_{IN}} \right)}$$

The worst-case condition occurs at $V_{IN} = 2 \times V_{OUT}$, where:

$$I_{CIN} = \frac{I_{load}}{2}$$

For simplification, choose the input capacitor whose RMS current rating is greater than half of the maximum load current.

When electrolytic or tantalum capacitors are used, a small, high quality ceramic capacitor, i.e. 0.1 μ F, should be placed as close to the IC as possible. When ceramic capacitors are used, make sure that they have enough capacitance to maintain voltage ripple at input. The input voltage ripple caused by capacitance can be estimated by:

$$\Delta V_{IN} = \frac{I_{load}}{f_s \times C_{IN}} \times \frac{V_{OUT}}{V_{IN}} \times \left(1 - \frac{V_{OUT}}{V_{IN}} \right)$$

C_{IN} is the input capacitance.

10.3 Output capacitors selection

The output capacitor (C_{OUT}) is required to maintain the DC output voltage. Ceramic, tantalum, or low ESR electrolytic capacitors are recommended.

Low ESR capacitors are preferred to keep the output voltage ripple low. The output voltage ripple can be estimated by:

$$\Delta V_{OUT} = \frac{V_{OUT}}{f_s \times L} \times \left(1 - \frac{V_{OUT}}{V_{IN}} \right) \times \left(R_{ESR} + \frac{1}{8 \times f_s \times C_{OUT}} \right)$$

Where L is the inductor value, R_{ESR} is the equivalent series resistance (ESR) value of the output capacitor and C_{OUT} is the output capacitance value. In the case of ceramic capacitors, the impedance at the switching frequency is dominated by the capacitance. The output voltage ripple is mainly determined by the capacitance. For simplification, the output voltage ripple can be estimated by:

$$\Delta V_{OUT} = \frac{V_{OUT}}{8 \times f_s^2 \times L \times C_{OUT}} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right)$$

In the case of tantalum or electrolytic capacitors, the ESR dominates the impedance at the switching frequency. For simplification, the output ripple can be approximated to:

$$\Delta V_{OUT} = \frac{V_{OUT}}{f_s \times L} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right) \times R_{ESR}$$

The characteristics of the output capacitor also affect the stability of the regulator.

11 PCB Layout

11.1 Guideline

PCB layout is a critical portion of good power supply design. The following guidelines will help users design a PCB with the best power conversion efficiency, thermal performance, and minimized EMI.

1. The feedback network, resistor R₁ and R₂, should be kept close to FB pin. V_{out} sense path should stay away from noisy nodes, such as SW and BST signals and preferably through a layer on the other side of shielding layer.
2. The input bypass capacitor C₄ and C₅ must be placed as close as possible to the V_{IN} pin and ground. Grounding for both the input and output capacitors should consist of localized top side planes that connect to the GND pin and PAD. It is a good practice to place a ceramic cap near the V_{IN} pin to reduce the high frequency injection current.
3. The inductor L should be placed close to the SW pin to reduce magnetic and electrostatic noise.
4. The output capacitor, C₂ should be placed close to the junction of L. The L and C₂ trace should be as short as possible to reduce conducted and radiated noise and increase overall efficiency.
5. The ground connection for C₄, C₅ and C₂, C₃ should be as small as possible and connect to system ground plane at only one spot (preferably at the C_{OUT} ground point) to minimize injecting noise into system ground plane.

11.2 Example

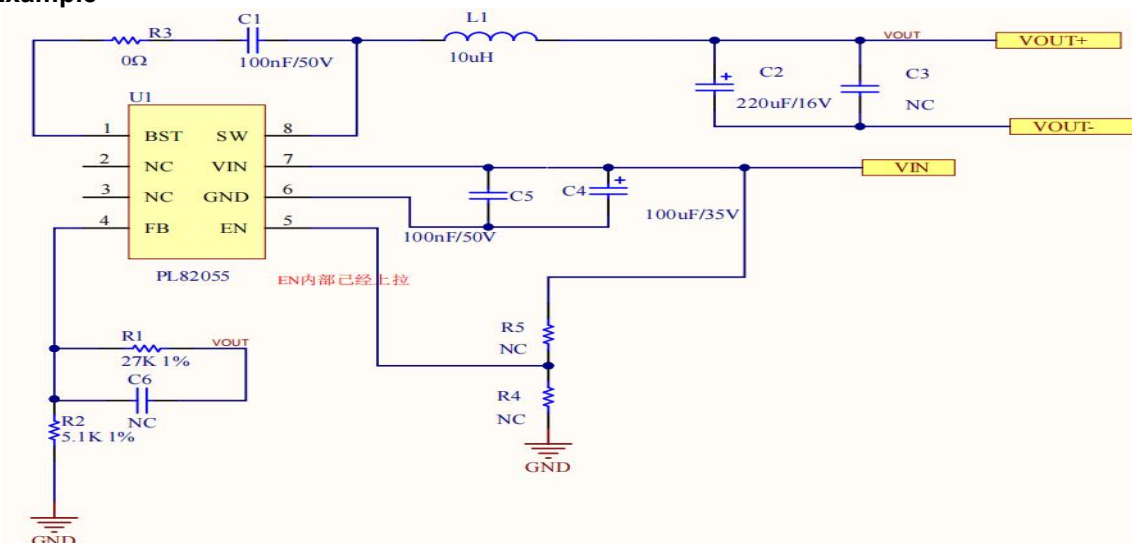


Fig. 11-2-1 Schematic

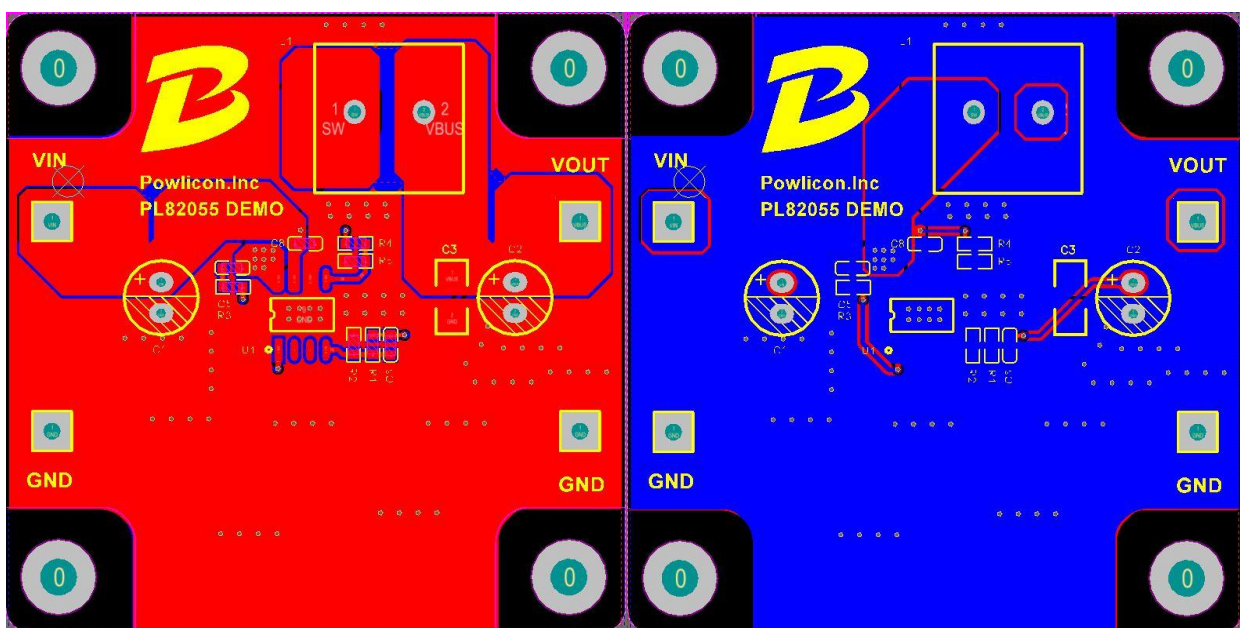
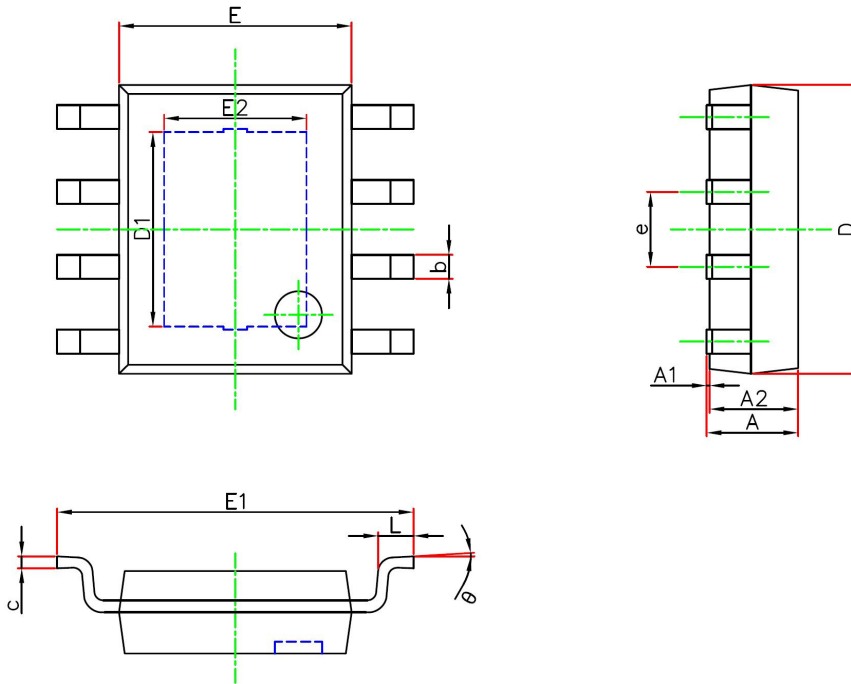


Fig. 11-2-2 PCB

12 Packaging Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.300	1.700	0.051	0.067
A1	0.000	0.100	0.000	0.004
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.700	5.100	0.185	0.201
D1	3.202	3.402	0.126	0.134
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
E2	2.313	2.513	0.091	0.099
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

IMPORTANT NOTICE

Powlicon Microelectronics Co., Ltd. assumes no responsibility for any error which may appear in this document. Powlicon Microelectronics Co., Ltd. reserves the right to change devices or specifications detailed herein at any time without notice. Powlicon Microelectronics Co., Ltd. does not assume any liability arising out of the application or use of any product described herein; neither it convey any license under its patent rights, nor the rights of others. Powlicon Microelectronics Co., Ltd. products are not authorized for use as critical components in life support devices or systems without written approval letter from the Chief Executive Officer of Powlicon Microelectronics Co., Ltd. The user of products in such applications shall assume all risks of such use and will agree to not hold against Powlicon Microelectronics Co., Ltd. for any damage.